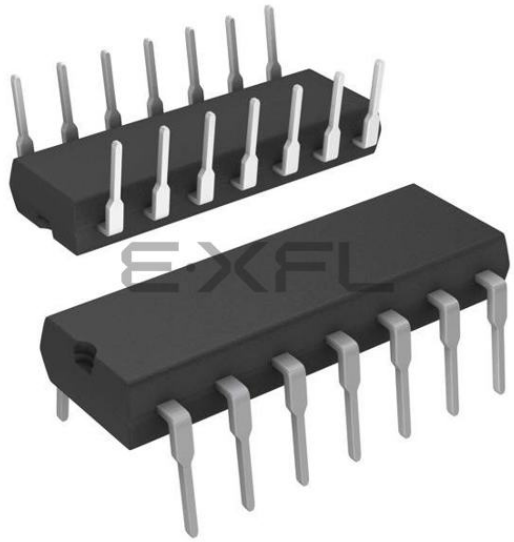

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	12
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	14-DIP (0.300", 7.62mm)
Supplier Device Package	14-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f688-e-p

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TABLE 2-4: PIC16F688 SPECIAL FUNCTION REGISTERS SUMMARY BANK 3

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR/BOR	Page
Bank 3											
180h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	20, 117
181h	OPTION_REG	$\overline{RAPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	14, 117
182h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	19, 117
183h	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	13, 117
184h	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	20, 117
185h	TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	--11 1111	33, 117
186h	—	Unimplemented								—	—
187h	TRISC	—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	--11 1111	42, 117
188h	—	Unimplemented								—	—
189h	—	Unimplemented								—	—
18Ah	PCLATH	—	—	—	Write Buffer for upper 5 bits of Program Counter					---0 0000	19, 117
18Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF(2)	0000 000x	15, 117
18Ch	—	Unimplemented								—	—
18Dh	—	Unimplemented								—	—
190h	—	Unimplemented								—	—
191h	—	Unimplemented								—	—
192h	—	Unimplemented								—	—
193h	—	Unimplemented								—	—
194h	—	Unimplemented								—	—
195h	—	Unimplemented								—	—
196h	—	Unimplemented								—	—
19Ah	—	Unimplemented								—	—
19Bh	—	Unimplemented								—	—
199h	—	Unimplemented								—	—
19Ah	—	Unimplemented								—	—
19Bh	—	Unimplemented								—	—
19Ch	—	Unimplemented								—	—
19Dh	—	Unimplemented								—	—
19Eh	—	Unimplemented								—	—
19Fh	—	Unimplemented								—	—

Legend: – = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

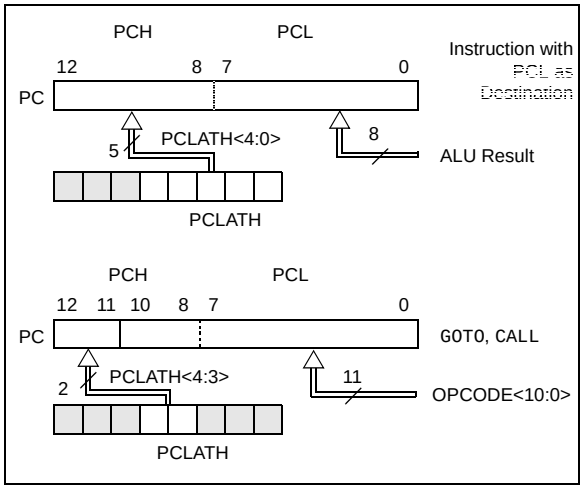
Note 1: Other (non Power-up) Resets include $\overline{MCLR}$ Reset and Watchdog Timer Reset during normal operation.

2: $\overline{MCLR}$ and WDT Reset does not affect the previous value data latch. The RAIF bit will be cleared upon Reset but will set again if the mismatched exists.

2.3 PCL and PCLATH

The Program Counter (PC) is 13 bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any Reset, the PC is cleared. Figure 2-3 shows the two situations for the loading of the PC. The upper example in Figure 2-3 shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in Figure 2-3 shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> → PCH).

FIGURE 2-3: LOADING OF PC IN DIFFERENT SITUATIONS



2.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When performing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block). Refer to the Application Note AN556, *"Implementing a Table Read"* (DS00556).

2.3.2 STACK

The PIC16F688 family has an 8-level x 13-bit wide hardware stack (see Figure 2-1). The stack space is not part of either program or data space and the Stack Pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1:	There are no Status bits to indicate Stack Overflow or Stack Underflow conditions.
2:	There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions or the vectoring to an interrupt address.

3.3 Clock Source Modes

Clock source modes can be classified as external or internal.

- External Clock modes rely on external circuitry for the clock source. Examples are: oscillator modules (EC mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (RC) mode circuits.
- Internal clock sources are contained internally within the oscillator module. The oscillator module has two internal oscillators: the 8 MHz High-Frequency Internal Oscillator (HFINTOSC) and the 31 kHz Low-Frequency Internal Oscillator (LFINTOSC).

The system clock can be selected between external or internal clock sources via the System Clock Select (SCS) bit of the OSCCON register. See **Section 3.6 "Clock Switching"** for additional information.

3.4 External Clock Modes

3.4.1 OSCILLATOR START-UP TIMER (OST)

If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module. When switching between clock sources, a delay is required to allow the new clock to stabilize. These oscillator delays are shown in Table 3-1.

In order to minimize latency between external oscillator start-up and code execution, the Two-Speed Clock Start-up mode can be selected (see **Section 3.7 "Two-Speed Clock Start-up Mode"**).

TABLE 3-1: OSCILLATOR DELAY EXAMPLES

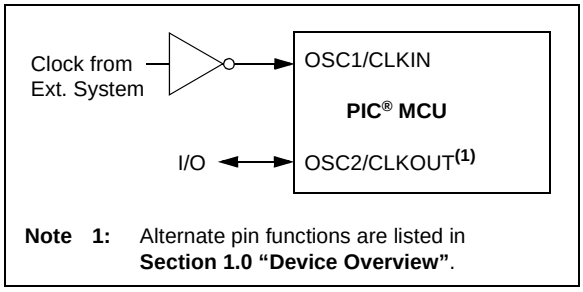
Switch From	Switch To	Frequency	Oscillator Delay
Sleep/POR	LFINTOSC HFINTOSC	31 kHz 125 kHz to 8 MHz	Oscillator Warm-Up Delay (TWARM)
Sleep/POR	EC, RC	DC – 20 MHz	2 instruction cycles
LFINTOSC (31 kHz)	EC, RC	DC – 20 MHz	1 cycle of each
Sleep/POR	LP, XT, HS	32 kHz to 20 MHz	1024 Clock Cycles (OST)
LFINTOSC (31 kHz)	HFINTOSC	125 kHz to 8 MHz	1 μs (approx.)

3.4.2 EC MODE

The External Clock (EC) mode allows an externally generated logic level as the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input and the OSC2 is available for general purpose I/O. Figure 3-2 shows the pin connections for EC mode.

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 3-2: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Alternate pin functions are listed in **Section 1.0 "Device Overview"**.

3.5.3 LFINTOSC

The Low-Frequency Internal Oscillator (LFINTOSC) is an uncalibrated 31 kHz internal clock source.

The output of the LFINTOSC connects to a postscaler and multiplexer (see Figure 3-1). Select 31 kHz, via software, using the IRCF<2:0> bits of the OSCCON register. See **Section 3.5.4 "Frequency Select Bits (IRCF)"** for more information. The LFINTOSC is also the frequency for the Power-up Timer (PWRT), Watchdog Timer (WDT) and Fail-Safe Clock Monitor (FSCM).

The LFINTOSC is enabled by selecting 31 kHz (IRCF<2:0> bits of the OSCCON register = 000) as the system clock source (SCS bit of the OSCCON register = 1), or when any of the following are enabled:

- Two-Speed Start-up IESO bit of the Configuration Word register = 1 and IRCF<2:0> bits of the OSCCON register = 000
- Power-up Timer (PWRT)
- Watchdog Timer (WDT)
- Fail-Safe Clock Monitor (FSCM)

The LF Internal Oscillator (LTS) bit of the OSCCON register indicates whether the LFINTOSC is stable or not.

3.5.4 FREQUENCY SELECT BITS (IRCF)

The output of the 8 MHz HFINTOSC and 31 kHz LFINTOSC connects to a postscaler and multiplexer (see Figure 3-1). The Internal Oscillator Frequency Select bits IRCF<2:0> of the OSCCON register select the frequency output of the internal oscillators. One of eight frequencies can be selected via software:

- 8 MHz
- 4 MHz (Default after Reset)
- 2 MHz
- 1 MHz
- 500 kHz
- 250 kHz
- 125 kHz
- 31 kHz (LFINTOSC)

Note:	Following any Reset, the IRCF<2:0> bits of the OSCCON register are set to '110' and the frequency selection is set to 4 MHz. The user can modify the IRCF bits to select a different frequency.

3.5.5 HF AND LF INTOSC CLOCK SWITCH TIMING

When switching between the LFINTOSC and the HFINTOSC, the new oscillator may already be shut down to save power (see Figure 3-6). If this is the case, there is a delay after the IRCF<2:0> bits of the OSCCON register are modified before the frequency selection takes place. The LTS and HTS bits of the OSCCON register will reflect the current active status of the LFINTOSC and HFINTOSC oscillators. The timing of a frequency selection is as follows:

1. IRCF<2:0> bits of the OSCCON register are modified.
2. If the new clock is shut down, a clock start-up delay is started.
3. Clock switch circuitry waits for a falling edge of the current clock.
4. CLKOUT is held low and the clock switch circuitry waits for a rising edge in the new clock.
5. CLKOUT is now connected with the new clock. LTS and HTS bits of the OSCCON register are updated as required.
6. Clock switch is complete.

See Figure 3-1 for more details.

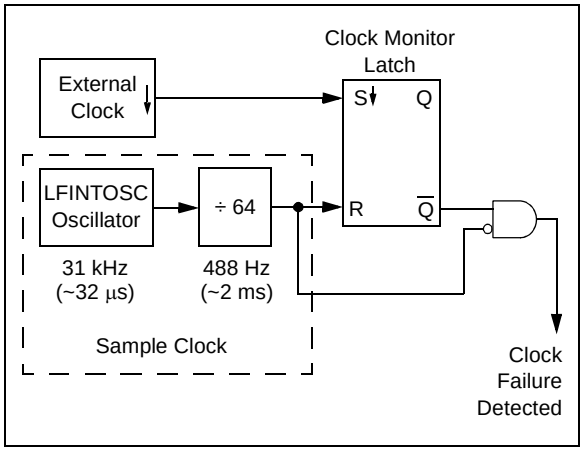
If the internal oscillator speed selected is between 8 MHz and 125 kHz, there is no start-up delay before the new frequency is selected. This is because the old and new frequencies are derived from the HFINTOSC via the postscaler and multiplexer.

Start-up delay specifications are located in the **Section 14.0 "Electrical Specifications"**, under the AC Specifications (Oscillator Module).

3.8 Fail-Safe Clock Monitor

The Fail-Safe Clock Monitor (FSCM) allows the device to continue operating should the external oscillator fail. The FSCM can detect oscillator failure any time after the Oscillator Start-up Timer (OST) has expired. The FSCM is enabled by setting the FCMEN bit in the Configuration Word register (CONFIG). The FSCM is applicable to all external oscillator modes (LP, XT, HS, EC, RC and RCIO).

FIGURE 3-8: FSCM BLOCK DIAGRAM



3.8.1 FAIL-SAFE DETECTION

The FSCM module detects a failed oscillator by comparing the external oscillator to the FSCM sample clock. The sample clock is generated by dividing the LFINTOSC by 64. See Figure 3-8. Inside the fail detector block is a latch. The external clock sets the latch on each falling edge of the external clock. The sample clock clears the latch on each rising edge of the sample clock. A failure is detected when an entire half-cycle of the sample clock elapses before the primary clock goes low.

3.8.2 FAIL-SAFE OPERATION

When the external clock fails, the FSCM switches the device clock to an internal clock source and sets the bit flag OSFIF of the PIR2 register. Setting this flag will generate an interrupt if the OSFIE bit of the PIE2 register is also set. The device firmware can then take steps to mitigate the problems that may arise from a failed clock. The system clock will continue to be sourced from the internal clock source until the device firmware successfully restarts the external oscillator and switches back to external operation.

The internal clock source chosen by the FSCM is determined by the IRCF<2:0> bits of the OSCCON register. This allows the internal oscillator to be configured before a failure occurs.

3.8.3 FAIL-SAFE CONDITION CLEARING

The Fail-Safe condition is cleared after a Reset, executing a SLEEP instruction or toggling the SCS bit of the OSCCON register. When the SCS bit is toggled, the OST is restarted. While the OST is running, the device continues to operate from the INTOSC selected in OSCCON. When the OST times out, the Fail-Safe condition is cleared and the device will be operating from the external clock source. The Fail-Safe condition must be cleared before the OSFIF flag can be cleared.

3.8.4 RESET OR WAKE-UP FROM SLEEP

The FSCM is designed to detect an oscillator failure after the Oscillator Start-up Timer (OST) has expired. The OST is used after waking up from Sleep and after any type of Reset. The OST is not used with the EC or RC Clock modes so that the FSCM will be active as soon as the Reset or wake-up has completed. When the FSCM is enabled, the Two-Speed Start-up is also enabled. Therefore, the device will always be executing code while the OST is operating.

Note:	Due to the wide range of oscillator start-up times, the Fail-Safe circuit is not active during oscillator start-up (i.e., after exiting Reset or Sleep). After an appropriate amount of time, the user should check the OSTS bit of the OSCCON register to verify the oscillator start-up and that the system clock switchover has successfully completed.

FIGURE 3-9: FSCM TIMING DIAGRAM

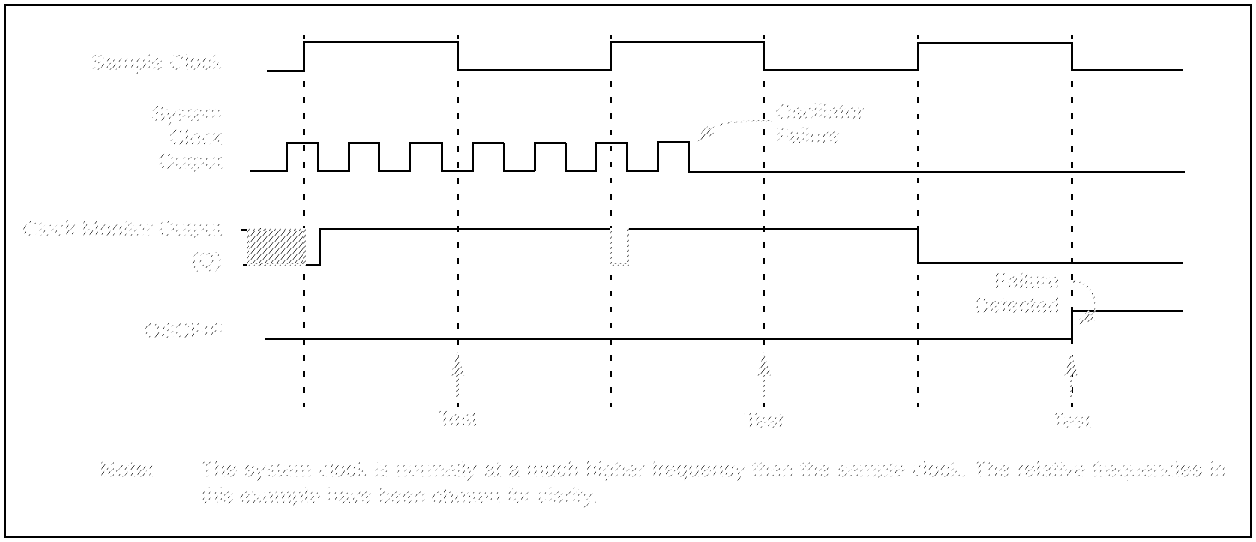


TABLE 3-2: SUMMARY OF REGISTERS ASSOCIATED WITH CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets(1)
CONFIG(2)	$\overline{CPD}$	$\overline{CP}$	MCLRE	$\overline{PWRTE}$	WDTE	FOSC2	FOSC1	FOSC0	—	—
INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 000x	0000 000x
OSCCON	—	IRCF2	IRCF1	IRCF0	OSTS	HTS	LTS	SCS	-110 x000	-110 x000
OSCTUNE	—	—	—	TUN4	TUN3	TUN2	TUN1	TUN0	---0 0000	---u uuuu
PIE1	EEIE	ADIE	RCIE	C2IE	C1IE	OSFIE	TXIE	TMR1IE	0000 0000	0000 0000
PIR1	EEIF	ADIF	RCIF	C2IF	C1IF	OSFIF	TXIF	TMR1IF	0000 0000	0000 0000

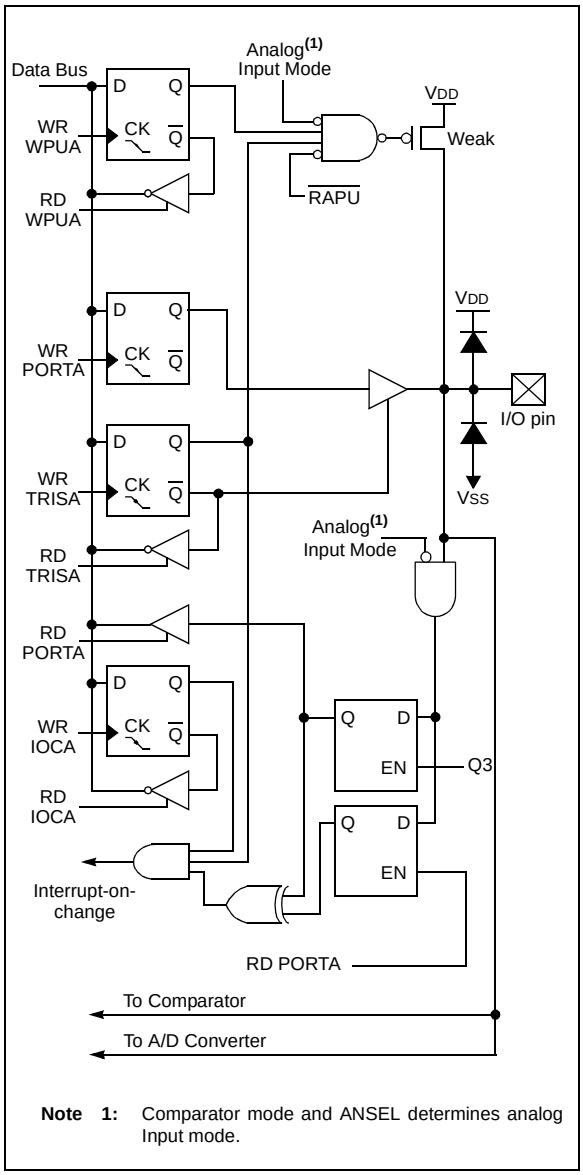
Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by oscillators.
Note 1: Other (non Power-up) Resets include $\overline{MCLR}$ Reset and Watchdog Timer Reset during normal operation.
2: See Configuration Word register (CONFIG) for operation of all register bits.

4.2.5.2 RA1/AN1/C1IN-/VREF/ICSPCLK

Figure 4-2 shows the diagram for this pin. The RA1 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the A/D
- an analog input to the comparator
- a voltage reference input for the A/D
- In-Circuit Serial Programming™ clock

FIGURE 4-2: BLOCK DIAGRAM OF RA1



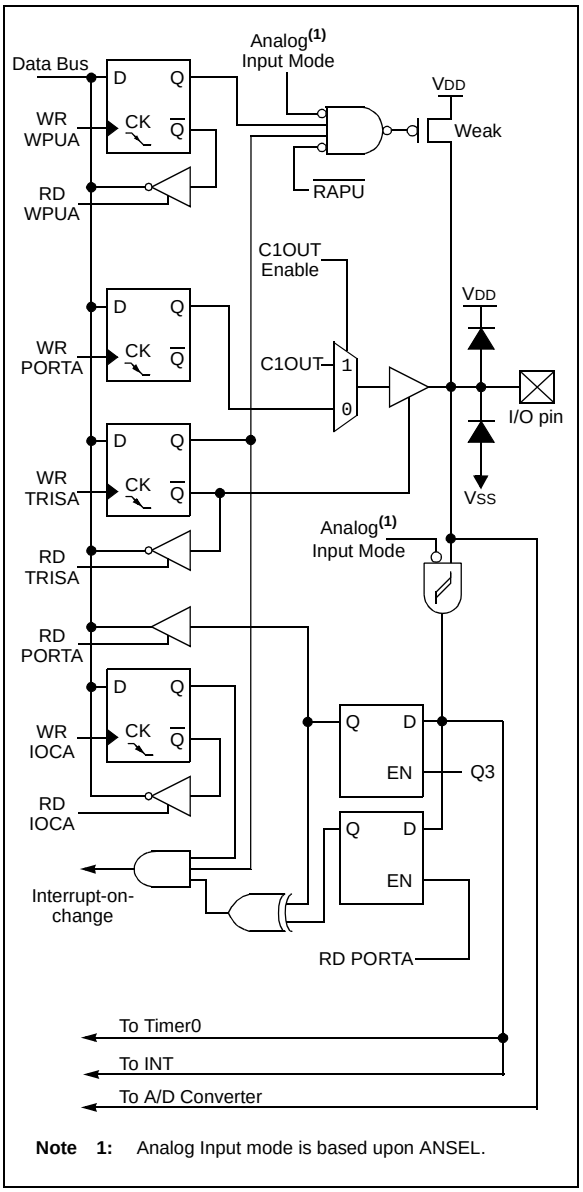
Note 1: Comparator mode and ANSEL determines analog Input mode.

4.2.5.3 RA2/AN2/T0CKI/INT/C1OUT

Figure 4-3 shows the diagram for this pin. The RA2 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the A/D
- the clock input for Timer0
- an external edge triggered interrupt
- a digital output from the comparator

FIGURE 4-3: BLOCK DIAGRAM OF RA2



Note 1: Analog Input mode is based upon ANSEL.

7.10 Comparator Voltage Reference

The Comparator Voltage Reference module provides an internally generated voltage reference for the comparators. The following features are available:

- Independent from Comparator operation
- Two 16-level voltage ranges
- Output clamped to VSS
- Ratiometric with VDD

The VRCON register (Figure 7-3) controls the Voltage Reference module shown in Figure 7-8.

7.10.1 INDEPENDENT OPERATION

The comparator voltage reference is independent of the comparator configuration. Setting the VREN bit of the VRCON register will enable the voltage reference.

7.10.2 OUTPUT VOLTAGE SELECTION

The CVREF voltage reference has 2 ranges with 16 voltage levels in each range. Range selection is controlled by the VRR bit of the VRCON register. The 16 levels are set with the VR<3:0> bits of the VRCON register.

The CVREF output voltage is determined by the following equations:

EQUATION 7-1: CVREF OUTPUT VOLTAGE

$$V_{RR} = 1 \text{ (low range):}$$
$$CV_{REF} = (VR<3:0>/24) \times V_{DD}$$
$$V_{RR} = 0 \text{ (high range):}$$
$$CV_{REF} = (V_{DD}/4) + (VR<3:0> \times V_{DD}/32)$$

The full range of VSS to VDD cannot be realized due to the construction of the module. See Figure 7-8.

7.10.3 OUTPUT CLAMPED TO VSS

The CVREF output voltage can be set to Vss with no power consumption by configuring VRCON as follows:

- VREN = 0
- VRR = 1
- VR<3:0> = 0000

This allows the comparator to detect a zero-crossing while not consuming additional CVREF module current.

7.10.4 OUTPUT RATIOMETRIC TO VDD

The comparator voltage reference is VDD derived and therefore, the CVREF output changes with fluctuations in VDD. The tested absolute accuracy of the Comparator Voltage Reference can be found in **Section 14.0 "Electrical Specifications"**.

REGISTER 7-3: VRCON: VOLTAGE REFERENCE CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
VREN	—	VRR	—	VR3	VR2	VR1	VR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **VREN:** CVREF Enable bit
1 = CVREF circuit powered on
0 = CVREF circuit powered down, no IDD drain and CVREF = VSS.

bit 6 **Unimplemented:** Read as '0'

bit 5 **VRR:** CVREF Range Selection bit
1 = Low range
0 = High range

bit 4 **Unimplemented:** Read as '0'

bit 3-0 **VR<3:0>:** CVREF Value Selection bits ($0 \leq$ VR<3:0> ≤ 15)
When VRR = 1: CVREF = (VR<3:0>/24) * VDD
When VRR = 0: CVREF = VDD/4 + (VR<3:0>/32) * VDD

10.3 EUSART Baud Rate Generator (BRG)

The Baud Rate Generator (BRG) is an 8-bit or 16-bit timer that is dedicated to the support of both the asynchronous and synchronous EUSART operation. By default, the BRG operates in 8-bit mode. Setting the BRG16 bit of the BAUDCTL register selects 16-bit mode.

The SPBRGH, SPBRG register pair determines the period of the free running baud rate timer. In Asynchronous mode the multiplier of the baud rate period is determined by both the BRGH bit of the TXSTA register and the BRG16 bit of the BAUDCTL register. In Synchronous mode, the BRGH bit is ignored.

Table 10-3 contains the formulas for determining the baud rate. Example 10-1 provides a sample calculation for determining the baud rate and baud rate error.

Typical baud rates and error values for various asynchronous modes have been computed for your convenience and are shown in Table 10-3. It may be advantageous to use the high baud rate (BRGH = 1), or the 16-bit BRG (BRG16 = 1) to reduce the baud rate error. The 16-bit BRG mode is used to achieve slow baud rates for fast oscillator frequencies.

Writing a new value to the SPBRGH, SPBRG register pair causes the BRG timer to be reset (or cleared). This ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

If the system clock is changed during an active receive operation, a receive error or data loss may result. To avoid this problem, check the status of the RCIDL bit to make sure that the receive operation is Idle before changing the system clock.

EXAMPLE 10-1: CALCULATING BAUD RATE ERROR

For a device with FOSC of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

$$Desired\ Baud\ Rate = \frac{FOSC}{64([SPBRGH:SPBRG] + 1)}$$

Solving for SPBRGH:SPBRG:

$$X = \frac{\frac{FOSC}{Desired\ Baud\ Rate}}{64} - 1$$

$$= \frac{\frac{16000000}{9600}}{64} - 1$$

$$= [25.042] = 25$$

$$Calculated\ Baud\ Rate = \frac{16000000}{64(25 + 1)}$$

$$= 9615$$

$$Error = \frac{Calc.\ Baud\ Rate - Desired\ Baud\ Rate}{Desired\ Baud\ Rate}$$

$$= \frac{(9615 - 9600)}{9600} = 0.16\%$$

TABLE 10-3: BAUD RATE FORMULAS

Configuration Bits			BRG/EUSART Mode	Baud Rate Formula
SYNC	BRG16	BRGH		
0	0	0	8-bit/Asynchronous	FOSC/[64 (n+1)]
0	0	1	8-bit/Asynchronous	FOSC/[16 (n+1)]
0	1	0	16-bit/Asynchronous	
0	1	1	16-bit/Asynchronous	FOSC/[4 (n+1)]
1	0	x	8-bit/Synchronous	
1	1	x	16-bit/Synchronous	

Legend: x = Don't care, n = value of SPBRGH, SPBRG register pair

TABLE 10-4: REGISTERS ASSOCIATED WITH THE BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
BAUDCTL	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	01-0 0-00	01-0 0-00
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
SPBRG	BRG7	BRG6	BRG5	BRG4	BRG3	BRG2	BRG1	BRG0	0000 0000	0000 0000
SPBRGH	BRG15	BRG14	BRG13	BRG12	BRG11	BRG10	BRG9	BRG8	0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	0000 0010	0000 0010

Legend: x = unknown, – = unimplemented read as '0'. Shaded cells are not used for the Baud Rate Generator.

REGISTER 11-2: WDTCON: WATCHDOG TIMER CONTROL REGISTER

U-0	U-0	U-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-0
—	—	—	WDTPS3	WDTPS2	WDTPS1	WDTPS0	SWDTEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **Unimplemented:** Read as '0'

bit 4-1 **WDTPS<3:0>:** Watchdog Timer Period Select bits

Bit Value = Prescale Rate

0000 = 1:32
0001 = 1:64
0010 = 1:128
0011 = 1:256
0100 = 1:512 (Reset value)
0101 = 1:1024
0110 = 1:2048
0111 = 1:4096
1000 = 1:8192
1001 = 1:16384
1010 = 1:32768
1011 = 1:65536
1100 = Reserved
1101 = Reserved
1110 = Reserved
1111 = Reserved

bit 0 **SWDTEN:** Software Enable or Disable the Watchdog Timer(1)

1 = WDT is turned on
0 = WDT is turned off (Reset value)

Note 1: If WDTE Configuration bit = 1, then WDT is always enabled, irrespective of this control bit. If WDTE Configuration bit = 0, then it is possible to turn WDT on/off with this control bit.

TABLE 11-8: SUMMARY OF REGISTERS ASSOCIATED WITH WATCHDOG TIMER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
WDTCON	—	—	—	WDTPS3	WDTPS2	WSTPS1	WDTPS0	SWDTEN	---0 1000	---0 1000
OPTION_REG	$\overline{\text{RAPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
CONFIG	$\overline{\text{CPD}}$	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE	FOSC2	FOSC1	FOSC0	—	—

Legend: Shaded cells are not used by the Watchdog Timer.

Note 1: See Register 11.0 for operation of all Configuration Word register bits.

MOVF	Move f
Syntax:	[*label*] MOVF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) → (dest)
Status Affected:	Z
Description:	The contents of register f is moved to a destination dependent upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.
Words:	1
Cycles:	1
Example:	MOVF FSR, 0 After Instruction W = value in FSR register Z = 1

MOVWF	Move W to f
Syntax:	[*label*] MOVWF f
Operands:	$0 \le f \le 127$
Operation:	(W) → (f)
Status Affected:	None
Description:	Move data from W register to register 'f'.
Words:	1
Cycles:	1
Example:	MOVW OPTION F Before Instruction OPTION = 0xFF W = 0x4F After Instruction OPTION = 0x4F W = 0x4F

MOVLW	Move literal to W
Syntax:	[*label*] MOVLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W)
Status Affected:	None
Description:	The eight-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.
Words:	1
Cycles:	1
Example:	MOVLW 0x5A After Instruction W = 0x5A

NOP	No Operation
Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.
Words:	1
Cycles:	1
Example:	NOP

13.2 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for all PIC MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

13.3 MPLAB C18 and MPLAB C30 C Compilers

The MPLAB C18 and MPLAB C30 Code Development Systems are complete ANSI C compilers for Microchip's PIC18 and PIC24 families of microcontrollers and the dsPIC30 and dsPIC33 family of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use not found with other compilers.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

13.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

13.5 MPLAB ASM30 Assembler, Linker and Librarian

MPLAB ASM30 Assembler produces relocatable machine code from symbolic assembly language for dsPIC30F devices. MPLAB C30 C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire dsPIC30F instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

13.6 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C18 and MPLAB C30 C Compilers, and the MPASM and MPLAB ASM30 Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

14.3 DC Characteristics: PIC16F688-I (Industrial)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
Param No.	Device Characteristics	Min	Typ†	Max	Units	Conditions	
						VDD	Note
D020	**Power-down Base Current(IPD)(2)**	—	0.05	1.2	µA	2.0	WDT, BOR, Comparators, VREF and T1OSC disabled
		—	0.15	1.5	µA	3.0	
		—	0.35	1.8	µA	5.0	
		—	150	500	nA	3.0	-40°C ≤ TA ≤ +25°C
D021		—	1.0	2.2	µA	2.0	WDT Current(1)
		—	2.0	4.0	µA	3.0	
		—	3.0	7.0	µA	5.0	
D022		—	42	60	µA	3.0	BOR Current(1)
		—	85	122	µA	5.0	
D023		—	32	45	µA	2.0	Comparator Current(1), both comparators enabled
		—	60	78	µA	3.0	
		—	120	160	µA	5.0	
D024		—	30	36	µA	2.0	CVREF Current(1) (high range)
		—	45	55	µA	3.0	
		—	75	95	µA	5.0	
D025*		—	39	47	µA	2.0	CVREF Current(1) (low range)
		—	59	72	µA	3.0	
		—	98	124	µA	5.0	
D026		—	4.5	7.0	µA	2.0	T1OSC Current(1), 32.768 kHz
		—	5.0	8.0	µA	3.0	
		—	6.0	12	µA	5.0	
D027		—	0.30	1.6	µA	3.0	A/D Current(1), no conversion in progress
		—	0.36	1.9	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.

14.7 Timing Parameter Symbology

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

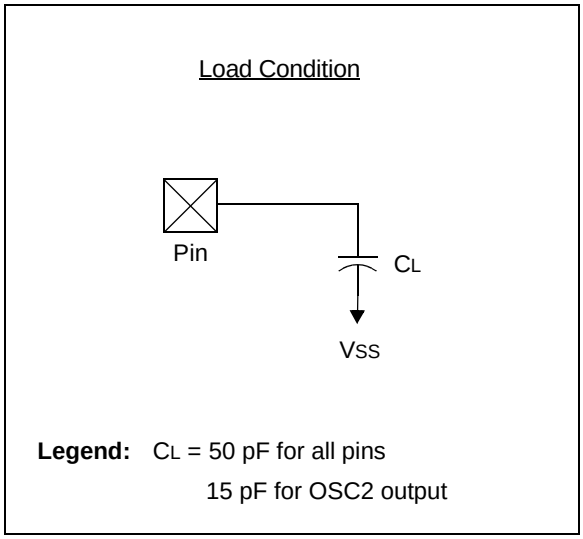
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O PORT	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 14-3: LOAD CONDITIONS



Legend: CL = 50 pF for all pins
15 pF for OSC2 output

TABLE 14-8: PIC16F688 A/D CONVERTER (ADC) CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
AD01	NR	Resolution	—	—	10 bits	bit	
AD02	EIL	Integral Error	—	—	±1	LSb	VREF = 5.12V
AD03	EDL	Differential Error	—	—	±1	LSb	No missing codes to 10 bits VREF = 5.12V
AD04	EOFF	Offset Error	—	—	±1	LSb	VREF = 5.12V
AD07	EGN	Gain Error	—	—	±1	LSb	VREF = 5.12V
AD06 AD06A	VREF	Reference Voltage(1)	2.2 2.7	—	— VDD	V	 Absolute minimum to ensure 1 LSb accuracy
AD07	VAIN	Full-Scale Range	VSS	—	VREF	V	
AD08	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	
AD09*	IREF	VREF Input Current(1)	10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN.
			—	—	50	μA	During A/D conversion cycle.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADC VREF is from external VREF or VDD pin, whichever is selected as reference input.

TABLE 14-9: PIC16F688 A/D CONVERSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
AD130*	TAD	A/D Clock Period	1.6	—	9.0	µs	TOSC-based, VREF ≥ 3.0V
			3.0	—	9.0	µs	TOSC-based, VREF full range
		A/D Internal RC Oscillator Period					ADCS<1:0> = 11 (ADRC mode)
			3.0	6.0	9.0	µs	At VDD = 2.5V
			1.6	4.0	6.0	µs	At VDD = 5.0V
AD131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	11	—	TAD	Set GO/$\overline{\text{DONE}}$ bit to new data in A/D Result register
AD132*	TACQ	Acquisition Time		11.5	—	µs	
AD133*	TAMP	Amplifier Settling Time	—	—	5	µs	
AD134	TGO	Q4 to A/D Clock Start	—	TOSC/2	—	—	
			—	TOSC/2 + TCY	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRESH and ADRESL registers may be read on the following TCY cycle.

2: See **Section 8.3 "A/D Acquisition Requirements"** for minimum conditions.

FIGURE 15-4: MAXIMUM IDD vs. FOSC OVER VDD (HS MODE)

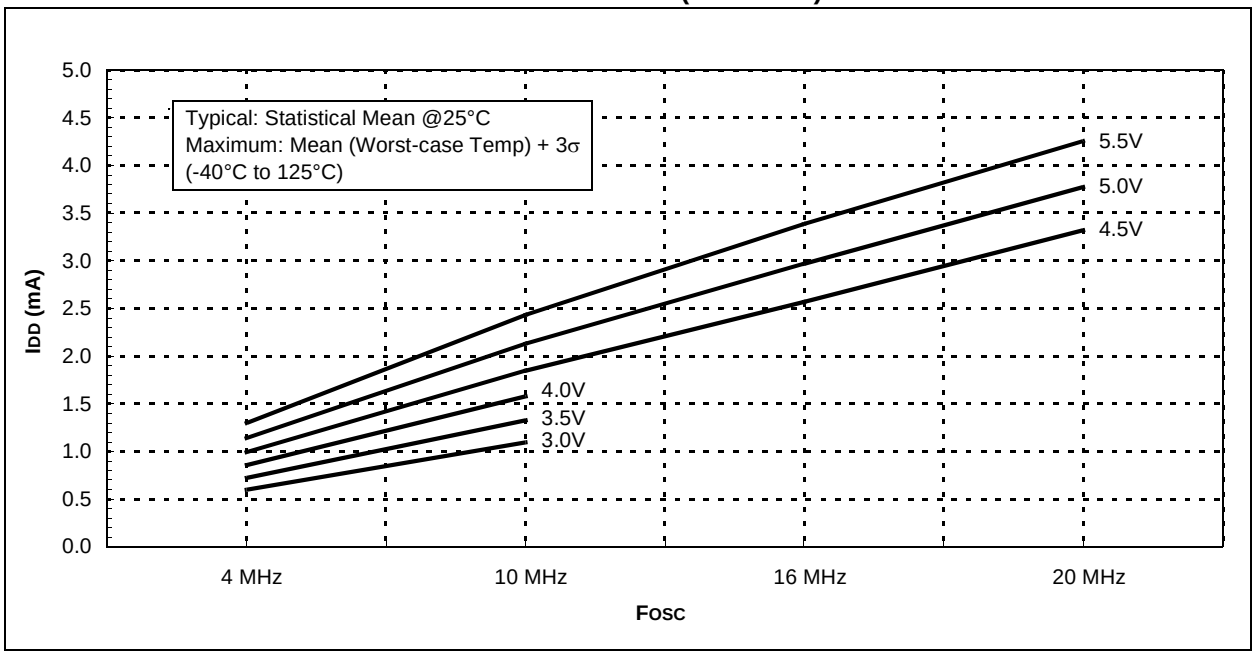


FIGURE 15-5: TYPICAL IDD vs. VDD OVER FOSC (XT MODE)

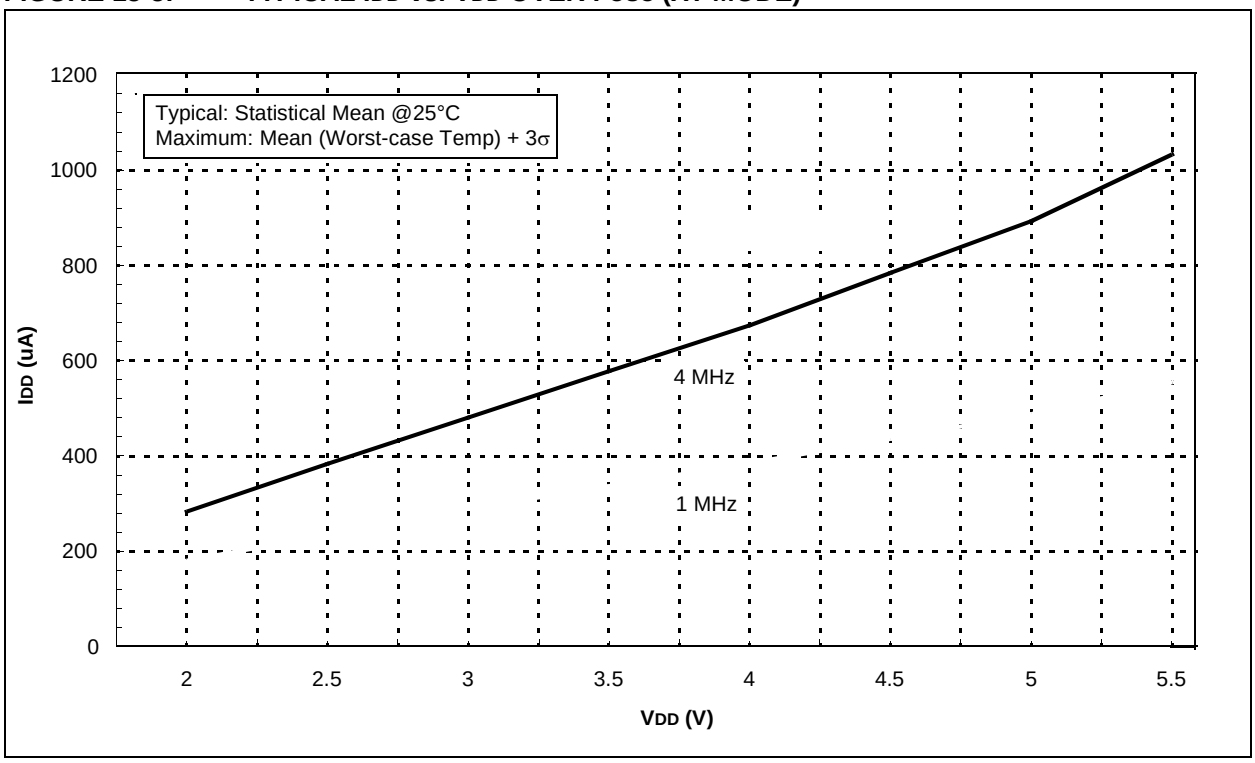


FIGURE 15-34: TYPICAL HFINTOSC START-UP TIMES vs. VDD OVER TEMPERATURE

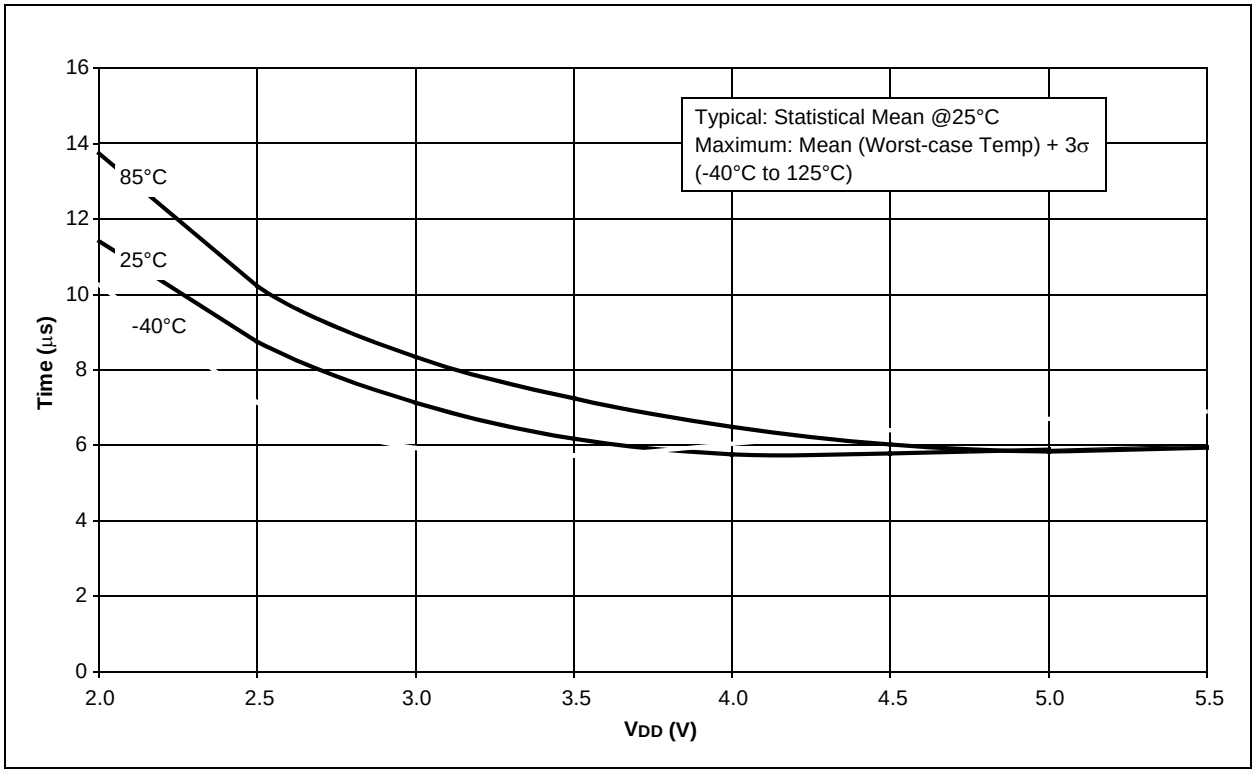
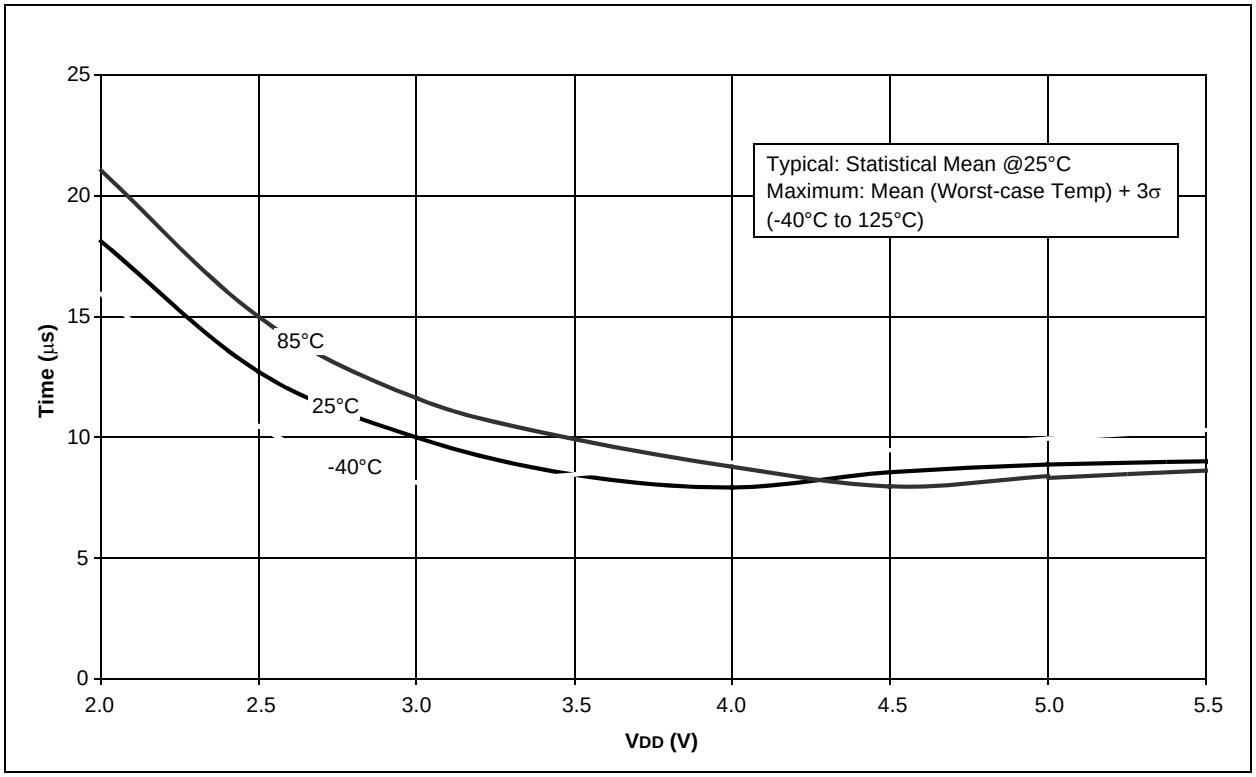
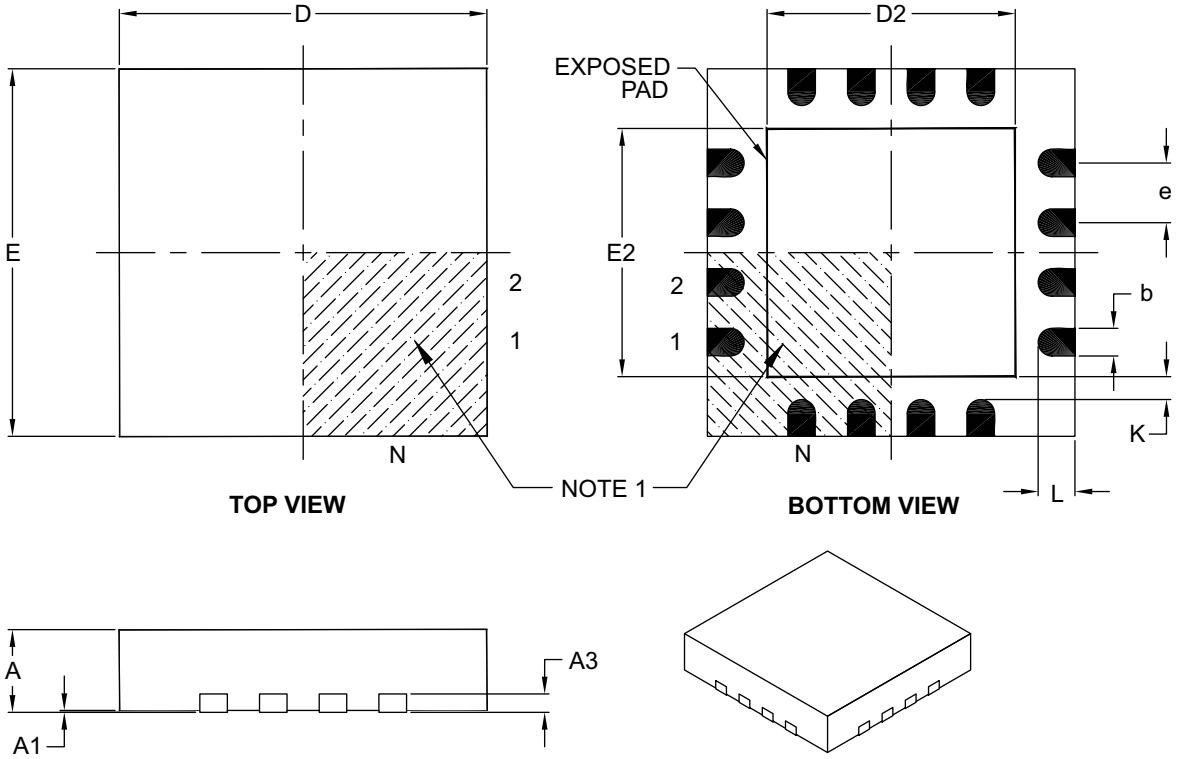


FIGURE 15-35: MAXIMUM HFINTOSC START-UP TIMES vs. VDD OVER TEMPERATURE



16-Lead Plastic Quad Flat, No Lead Package (ML) – 4x4x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.50	2.65	2.80
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.50	2.65	2.80
Contact Width	b	0.25	0.30	0.35
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-127B